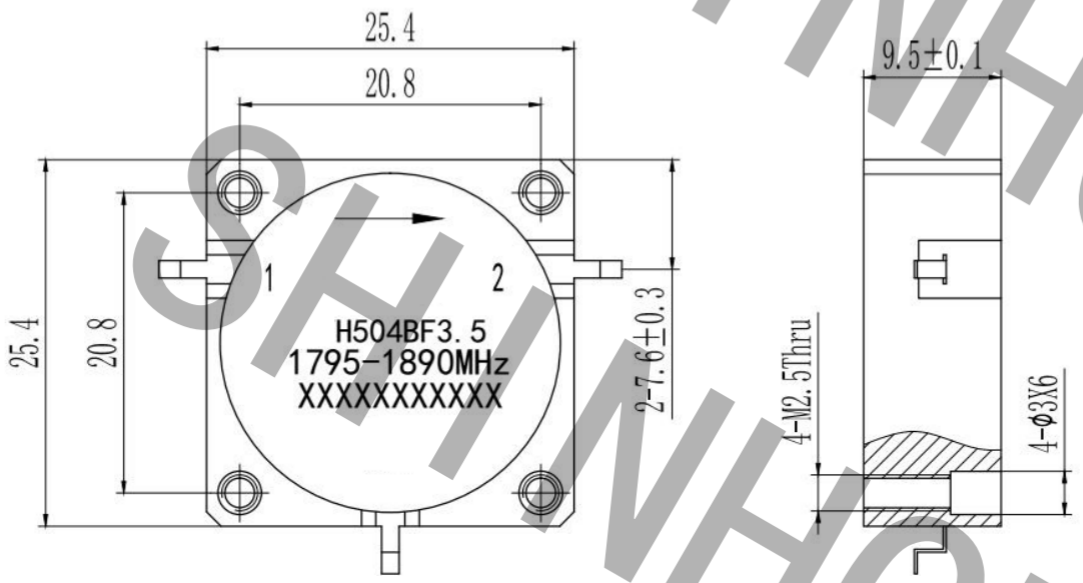
1.Features

UMTS, LTE Band
PCB Soldering Re-flow
Wide Operation Temperature Range -40~ 85℃
Compact Package Design for PCB Applications

2.Dimensions Unit:mm



3.Specifications

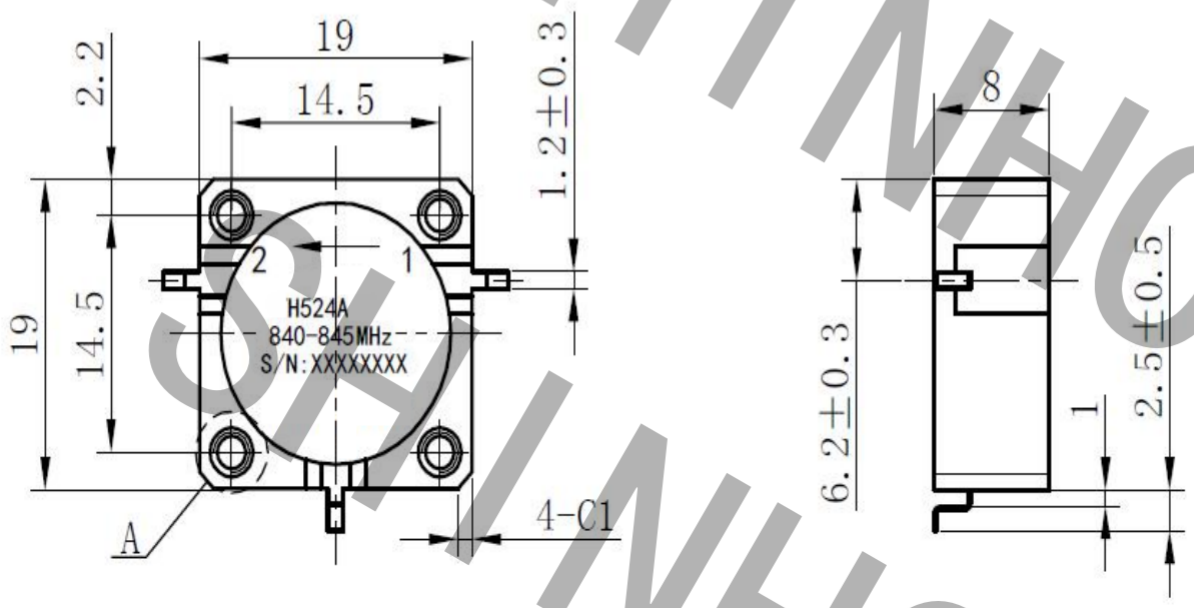
Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
H504B3.5[850-900]MHz	0.850	0.900	0.8750	0.050	25	0.2	1.12	250	-70
H504B3.0[850-900]MHz	0.850	0.900	0.8750	0.050	25	0.2	1.12	250	-72
H504B3.0[925-960]MHz	0.925	0.960	0.9425	0.035	25	0.2	1.12	250	-75
H504B3.5[925-960]MHz	0.925	0.960	0.9425	0.035	25	0.2	1.12	250	-75
H504B3.0[1795-1890]MHz	1.795	1.890	1.8425	0.095	25	0.2	1.12	250	-75
H504B3.5[1795-1890]MHz	1.795	1.890	1.8425	0.095	25	0.2	1.12	250	-75
H504B3.0[2110-2170]MHz	2.110	2.170	2.1400	0.060	25	0.2	1.12	250	-75
H504B3.5[2110-2170]MHz	2.110	2.170	2.1400	0.060	25	0.2	1.12	250	-75

SHINHOM

1.Features

UMTS, LTE Band
PCB Soldering Re-flow
Wide Operation Temperature Range -40~ 85℃
Compact Package Design for PCB Applications

2.Dimensions Unit:mm



3.Specifications

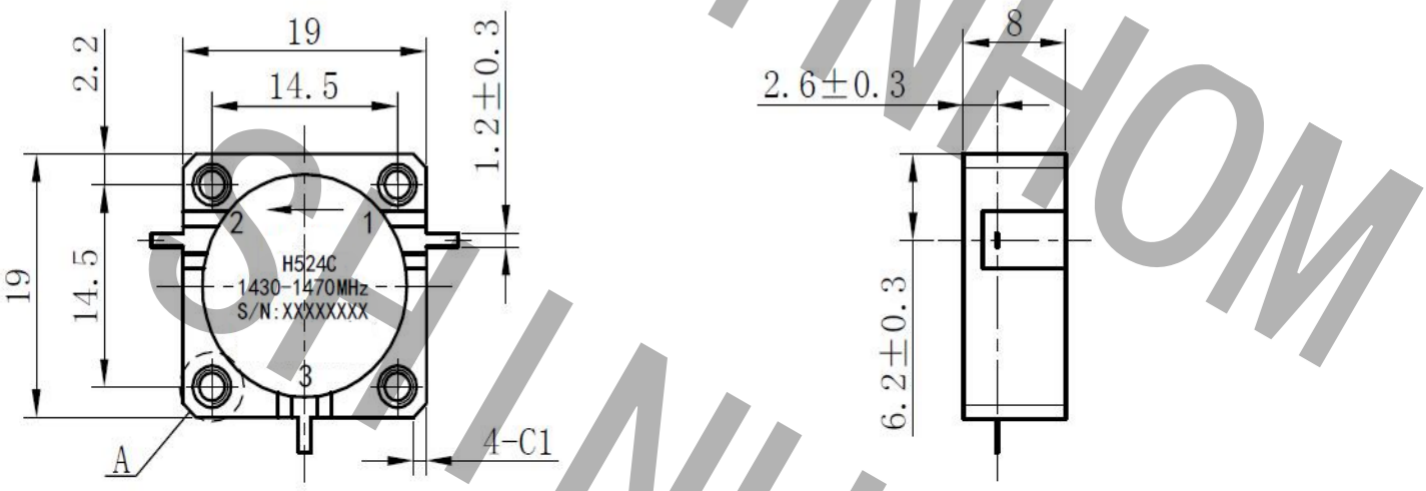
Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
H524A [840-845]MHz	0.840	0.845	0.8425	0.005	20	0.35	1.2	100	
H524A [902-928MHz	0.902	0.928	0.9150	0.026	22	0.3	1.17	100	
H524A [930-960MHz	0.930	0.960	0.9450	0.030	22	0.3	1.17	100	
H524A [1805-2170MHz	1.805	2.170	1.8875	0.165	22	0.3	1.17	150	-65
H524A [1900-3000MHz	1.900	3.000	2.450	1.100	20	0.35	1.2	100	-60

SHINHOM

1.Features

UMTS, LTE Band
PCB Soldering Re-flow
Wide Operation Temperature Range -40~ 85℃
Compact Package Design for PCB Applications

2.Dimensions Unit:mm



3.Specifications

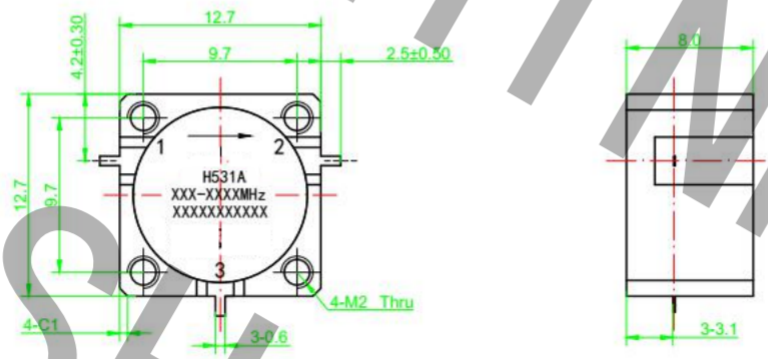
Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
H524C[1430-1470]MHz	1.430	1.470	1.4500	0.040	25	0.25	1.15	150	-70
H524C[1805-1920]MHz	1.805	1.920	1.8625	0.115	23	0.28	1.17	150	
H524C[1840-1920]MHz	1.840	1.920	1.8800	0.080	23	0.25	1.17	150	
H524C[2110-2170]MHz	2.110	2.170	2.1400	0.060	23	0.25	1.17	150	
H524C[2300-2400]MHz	2.300	2.400	2.3500	0.100	23	0.25	1.17	150	
H524C[2300-2700]MHz	2.300	2.700	2.500	0.400	20	0.4	1.22	150	
H524C[2555-2655]MHz	2.555	2.655	2.605	0.100	23	0.25	1.17	100	
H524C[2500-2700]MHz	2.500	2.700	2.600	0.200	23	0.25	1.15	100	
H524C[3400-3800]MHz	3.400	3.800	3.600	0.400	23	0.25	2.3	100	
H524C[4100-4400]MHz	4.100	4.400	4.250	0.300	22	0.4	1.2	30	
H524C[4750-5100]MHz	4.750	5.100	4.925	0.350	22	0.35	1.2	10	

SHINHOM

1.Features

UMTS, LTE Band
PCB Soldering Re-flow
Wide Operation Temperature Range -40~ 85℃
Compact Package Design for PCB Applications

2.Dimensions Unit:mm



3.Specifications

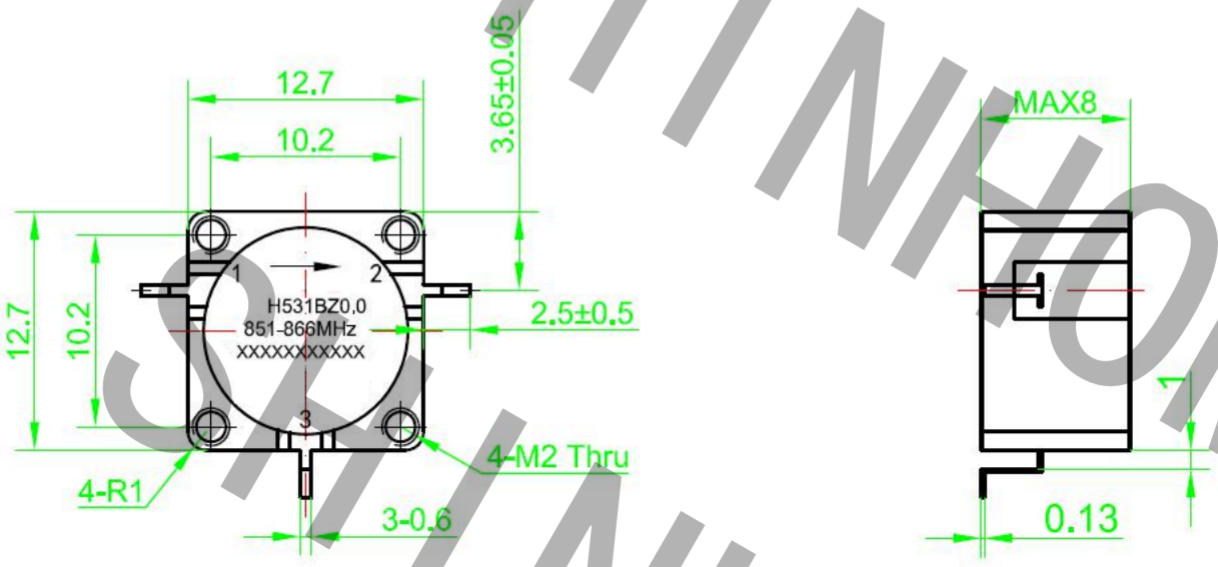
Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
H531A[1805-1880]MHz	1.805	1.880	1.8425	0.075	22	0.35	1.17	100	
H531A[1805-2025]MHz	1.805	2.025	1.915	0.220	18	0.35	1.28	75	
H531A[2000-2100]MHz	2.000	2.100	2.0500	0.100	20	0.35	1.22	75	
H531A[2110-2170]MHz	2.110	2.170	2.140	0.060	22	0.3	1.17	100	
H531A[2100-2200]MHz	2.100	2.200	2.150	0.100	20	0.35	1.22	75	
H531A[2300-2400]MHz	2.300	2.400	2.350	0.100	23	0.3	1.15	75	
H531A[2400-2550]MHz	2.400	2.550	2.475	0.150	23	0.3	1.15	75	
H531A[2500-2700]MHz	2.500	2.700	2.600	0.200	22	0.3	1.17	100	-75

SHINHOM

1.Features

UMTS, LTE Band
PCB Soldering Re-flow
Wide Operation Temperature Range -40~ 85℃
Compact Package Design for PCB Applications

2.Dimensions Unit:mm



3.Specifications

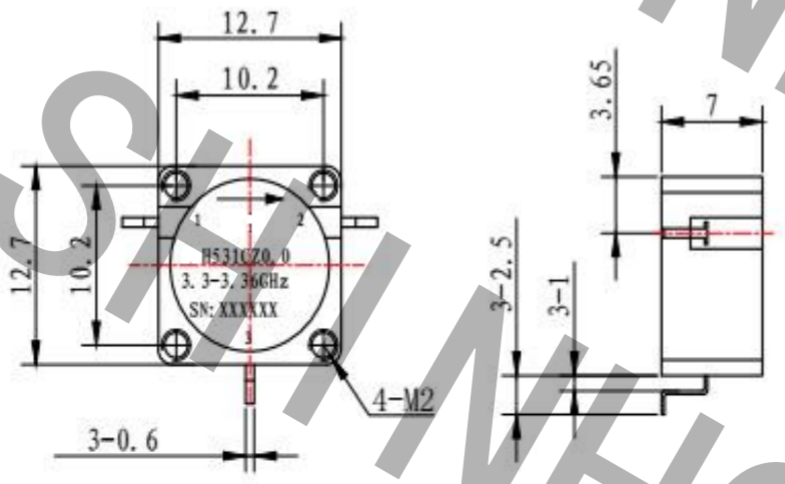
Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
H531B[851-866]MHz	0.851	0.866	0.8585	0.015	21	0.45	1.2	50	
H531B[865-880]MHz	0.865	0.880	0.8725	0.015	21	0.45	1.2	50	
H531B[930-960]MHz	0.930	0.960	0.9450	0.030	21	0.45	1.2	50	
H531B[1880-1920]MHz	1.880	1.920	1.900	0.040	23	0.3	1.15	100	
H531B[1805-2025]MHz	1.805	2.025	1.915	0.220	18	0.35	1.28	75	
H531B[1930-1995]MHz	1.930	1.995	1.963	0.065	23	0.3	1.15	100	
H531B[2110-2170]MHz	2.110	2.170	2.140	0.060	23	0.3	1.15	100	
H531B[2300-2400]MHz	2.300	2.400	2.350	0.100	23	0.3	1.15	100	
H531B[2400-2500]MHz	2.400	2.500	2.450	0.100	23	0.3	1.15	100	
H531B[2550-2650]MHz	2.550	2.650	2.600	0.100	23	0.3	1.15	100	

SHINHOM

1.Features

UMTS, LTE Band
PCB Soldering Re-flow
Wide Operation Temperature Range -40~ 85℃
Compact Package Design for PCB Applications

2.Dimensions Unit:mm



3.Specifications

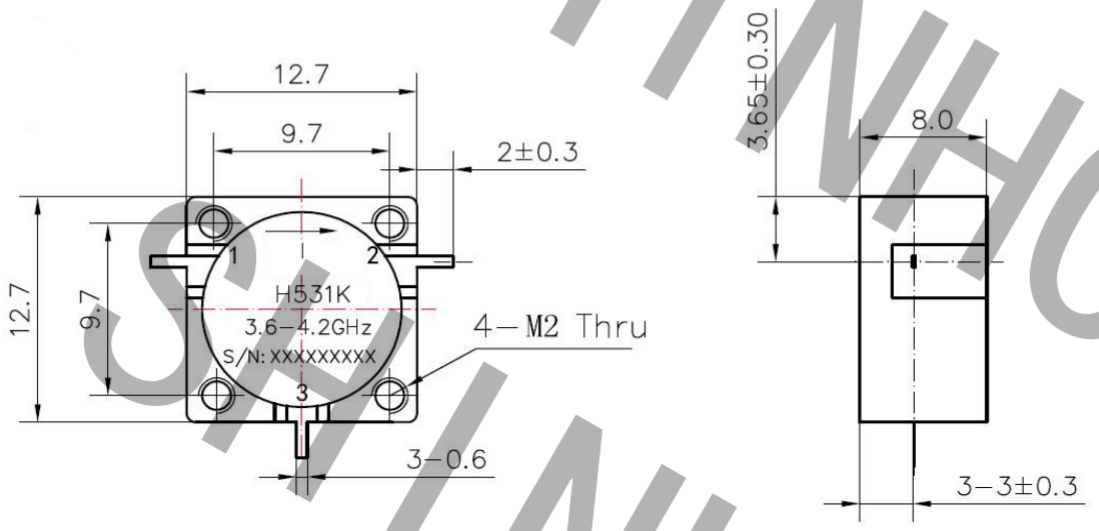
Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
H531C[3.3-3.36]MHz	3.300	3.360	3.3300	0.060	22	0.3	1.17	100	
H531C[3400-3700]MHz	3.400	3.700	3.5500	0.300	21	0.4	1.2	50	
H531C[5790-5890]MHz	5.790	5.890	5.8500	0.100	23	0.3	1.17	20	

SHINHOM SHINHOM SHINHOM

1.Features

UMTS, LTE Band
PCB Soldering Re-flow
Wide Operation Temperature Range -40~ 85℃
Compact Package Design for PCB Applications

2.Dimensions Unit:mm



3.Specifications

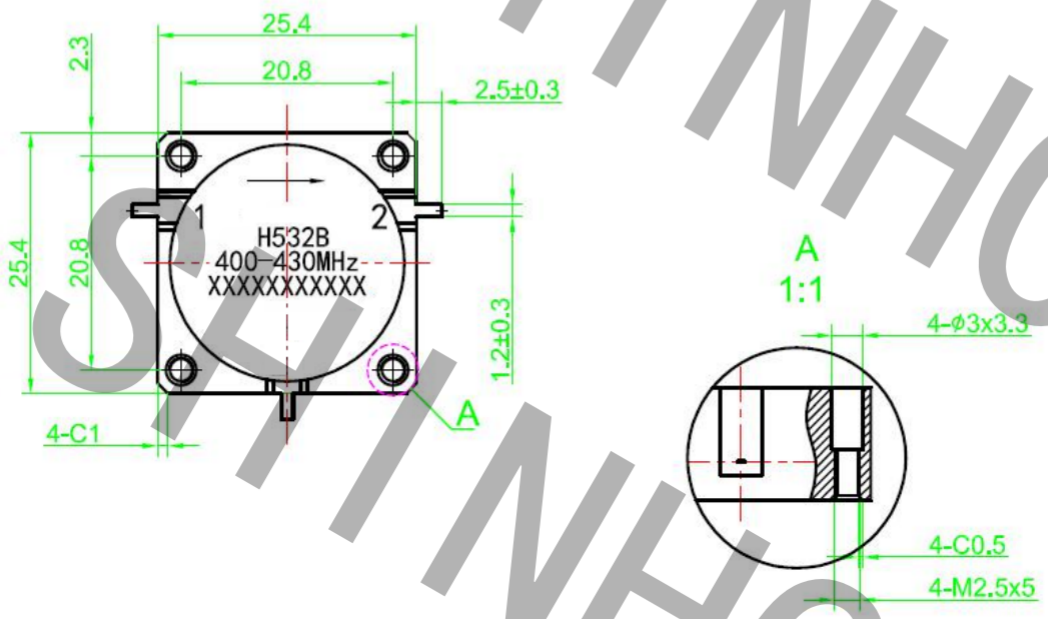
Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
H531K[3.6-4.2]GHz	3.600	4.200	3.9000	0.600	20	0.35	1.25	50	
H531K[3.7-4.13]GHz	3.700	4.130	3.9150	0.430	20	0.35	1.25	50	
H531K[4.4-5]GHz	4.400	5.000	4.7000	0.600	20	0.35	1.25	50	
H531K[5.15-5.9]GHz	5.150	5.900	5.5250	0.750	20	0.35	1.25	50	
H531K[7.1-7.5]GHz	7.100	7.500	7.300	0.400	22	0.4	1.2	10	
H531K[9.2-9.8]GHz	9.200	9.800	9.500	0.600	21	0.4	1.2	60	
H531K[10.1-10.6]GHz	10.100	10.600	10.350	0.500	22	0.4	1.2	20	

SHINHOM

1.Features

UMTS, LTE Band
PCB Soldering Re-flow
Wide Operation Temperature Range -40~ 85℃
Compact Package Design for PCB Applications

2.Dimensions Unit:mm



3.Specifications

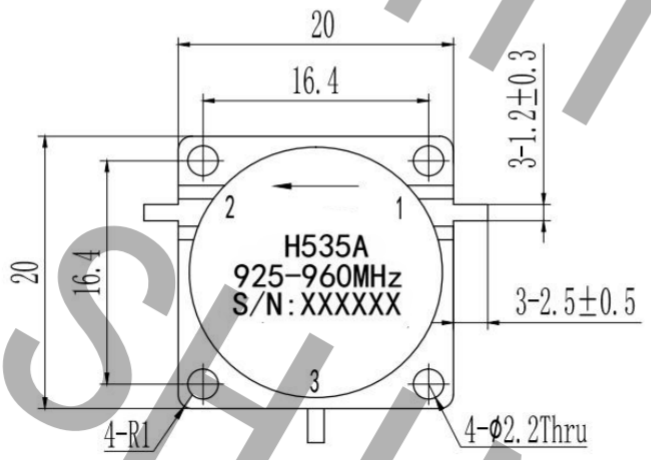
Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
H532B [400-430]MHz	0.400	0.430	0.4150	0.030	20	0.4	1.22	200	
H532B [566-600] MHz	0.566	0.600	0.5830	0.034	23	0.25	1.15	200	
H532B [566-678]MHz	0.566	0.678	0.6215	0.112	18	0.45	1.28	200	
H532B [600-684]MHz	0.600	0.684	0.6420	0.084	20	0.35	1.2	100	
H532B [600-700]MHz	0.600	0.700	0.6500	0.100	23	0.35	1.15	200	-65
H532B [700-740]MHz	0.700	0.740	0.7200	0.040	22	0.22	0.25	100	-70
H532B [758-803]MHz	0.758	0.803	0.7805	0.045	25	0.2	1.12	250	-70
H532B [925-960]MHz	0.925	0.960	0.9425	0.035	25	0.2	1.12	250	-75
H532B [1805-1880]MHz	1.805	1.880	1.838	0.075	23	0.25	1.15	300	-75
H532B [1930-1995]MHz	1.930	1.995	1.963	0.075	23	0.25	1.15	300	-75
H532B [2110-2170]MHz	2.110	2.170	2.140	0.060	25	0.2	1.12	250	-75

SHINHOM

1.Features

UMTS, LTE Band
PCB Soldering Re-flow
Wide Operation Temperature Range -40~ 85℃
Compact Package Design for PCB Applications

2.Dimensions Unit:mm



3.Specifications

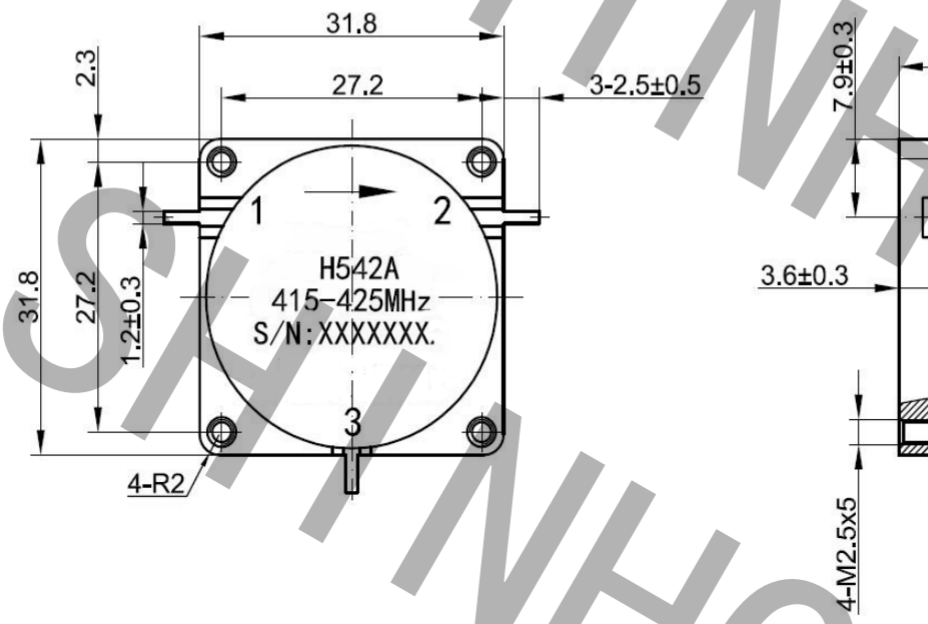
Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
H535A [825-835]MHz	0.825	0.835	0.8300	0.010	23	0.25	1.15	150	
H535A [840-845]MHz	0.840	0.845	0.8425	0.005	23	0.25	1.15	150	
H535A [860-960]MHz	0.860	0.960	0.9100	0.100	23	0.3	1.15	100	
H535A [880-915]MHz	0.880	0.915	0.8975	0.035	23	0.25	1.15	150	
H535A [925-960]MHz	0.925	0.960	0.9425	0.350	23	0.3	1.15	100	-74
H535A [960-980]MHz	0.960	0.980	0.9700	0.020	23	0.3	1.15	100	
H535A [1150-1250]MHz	1.150	1.250	1.200	0.200	23	0.25	1.15	100	
H535A [1400-1610]MHz	1.400	1.610	1.505	0.210	22	0.3	1.2	100	
H535A [1750-2120]MHz	1.750	2.120	1.925	0.370	20	0.35	1.2	150	
H535A [1805-1880]MHz	1.805	1.880	1.838	0.075	23	0.25	1.15	150	
H535A [1880-1920]MHz	1.880	1.920	1.900	0.040	23	0.25	1.15	100	
H535A [2110-2170]MHz	2.110	2.170	2.140	0.060	23	0.25	1.15	100	
H535A [2300-2400]MHz	2.300	2.400	2.350	0.100	22	0.3	1.2	150	
H535A [2400-2500]MHz	2.400	2.500	2.450	0.100	23	0.25	1.2	150	
H535A [2500-2700]MHz	2.500	2.700	2.600	0.200	22	0.28	1.17	150	

SHINHOM SHINHOM SHINHOM

1.Features

UMTS, LTE Band
PCB Soldering Re-flow
Wide Operation Temperature Range -40~ 85℃
Compact Package Design for PCB Applications

2.Dimensions Unit:mm



3.Specifications

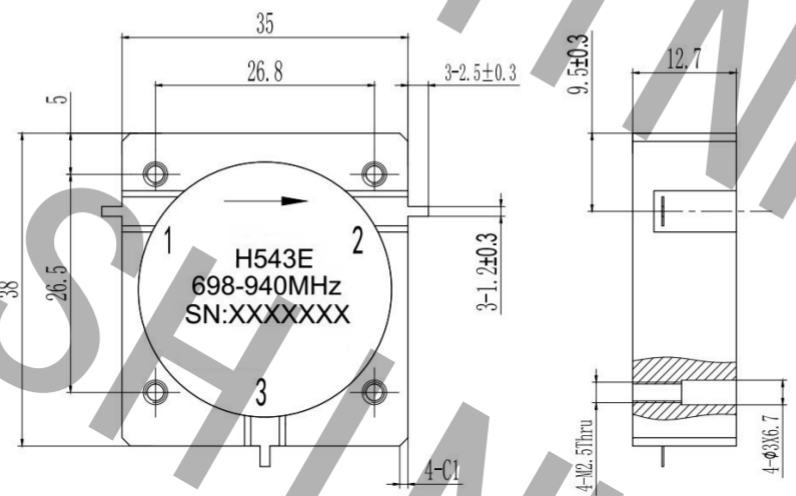
Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
H542A [415-425]MHz	0.415	0.425	0.4200	0.010	22	0.35	1.17	100	
H542A [470-510]MHz	0.470	0.510	0.4850	0.040	20	0.15	1.22	100	
H542A [560-680]MHz	0.560	0.680	0.6200	0.080	20	0.15	1.22	100	
H542A [700-960]MHz	0.700	0.960	0.8300	0.260	16	0.5	1.38	300	
H542A [925-960]MHz	0.925	0.960	0.9425	0.035	25	0.25	1.12	400	-75
H542A [1217-1238]MHz	1.217	1.238	1.2275	0.021	23	0.25	1.15	300	
H542A [1565-1586]MHz	1.565	1.586	1.5755	0.021	23	0.25	1.15	300	
H542A [1710-1785]MHz	1.710	1.785	1.7475	0.075	23	0.25	1.15	400	-70
H542A [1800-2175]MHz	1.800	2.175	1.9875	0.375	22	0.3	1.17	300	
H542A [1805-1880]MHz	1.805	1.880	1.838	0.075	25	0.2	1.12	350	-75
H542A [2110-2170]MHz	2.110	2.170	2.140	0.060	23	0.25	1.15	400	-75

SHINHOM

1.Features

UMTS, LTE Band
PCB Soldering Re-flow
Wide Operation Temperature Range -40~ 85℃
Compact Package Design for PCB Applications

2.Dimensions Unit:mm



3.Specifications

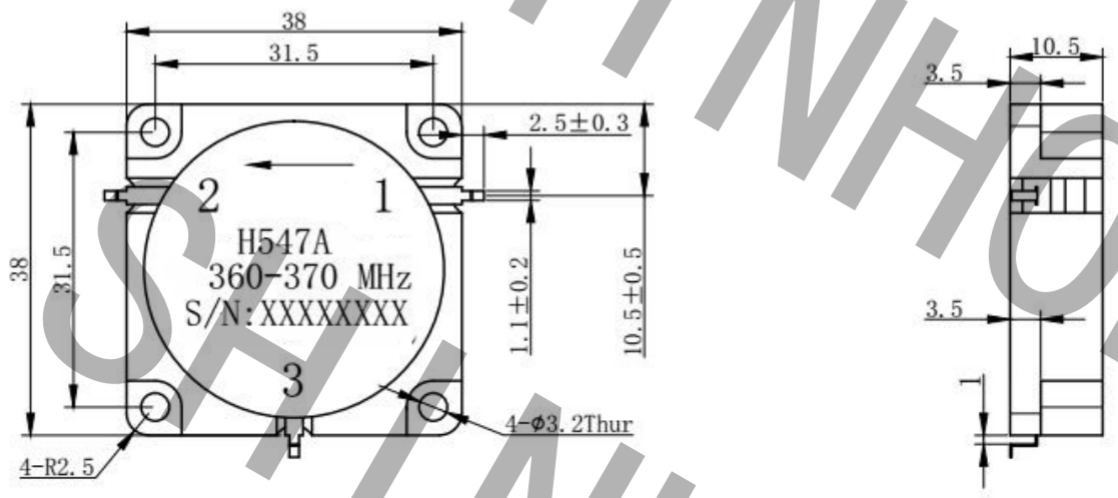
Part No.	Frequency (GHz)		Center Frequenc	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
H543E [330-350]MHz	0.330	0.350	0.340	0.020	20	0.45	1.22	100	
H543E [400-430]MHz	0.400	0.430	0.4250	0.030	22	0.25	1.17	200	
H543E [470-570]MHz	0.470	0.570	0.5200	0.100	20	0.4	1.2	200	
H543E [500-650]MHz	0.500	0.650	0.5750	0.150	18	0.45	1.28	100	
H543E [698-940]MHz	0.698	0.940	0.8190	0.242	18	0.4	1.28	100	

SHINHOM

1.Features

UMTS, LTE Band
PCB Soldering Re-flow
Wide Operation Temperature Range -40~ 85℃
Compact Package Design for PCB Applications

2.Dimensions Unit:mm



3.Specifications

Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
H547A0.0[360-370]MHz	0.360	0.370	0.365	0.010	23	0.25	1.15	150	
H547A0.0[395-435]MHz	0.385	0.435	0.4050	0.040	19	0.45	1.25	150	-60
H547A0.0[415-425]MHz	0.415	0.425	0.4200	0.010	22	0.35	1.17	200	
H547A0.0[470-520]MHz	0.470	0.520	0.4950	0.050	20	0.35	1.22	200	
H547A0.0[566-678]MHz	0.566	0.678	0.6220	0.112	20	0.45	1.22	150	-65

SHINHOM

Drop–in Circulator



Features:

UMTS, LTE Band
PCB Soldering Re–flow
Compact Package Design for PCB Applications

ELECTRICAL CHARACTERISTICS:

Model	Freq (GHz)	Bandwidth (MHz,max.)	Insertion Loss (dB,max.)	Isolation (dB,min.)	VSWR (dB,min.)	Average Power (W,max)	Temperature (℃)	Dimensions (mm)
H6060H	0.02–0.4	175	2	18	1.3	100	–10 – +60	60*60*25.5
H6466H	0.02–0.4	175	2	18	1.3	100	–10 – +60	64*66*22
H5050X	0.15–0.33	70	0.7	18	1.3	400	–30 – +70	50.8*50.8*14.8
H4545X	0.3–1	300	0.5	18	1.3	400	–30 – +70	45*45*13
H3538X	0.3–1.85	500	0.7	18	1.35	300	–30 – +70	35*35*11
H3838X	0.3–1.85	106	0.4	20	1.25	300	–30 – +70	38*38*11
H2525X	0.35–4	770	0.65	15	1.45	250	–30 – +70	25.4*25.4*10
H2020X	0.6–4	900	0.5	18	1.35	100	–30 – +70	20*20*8.6
H1919X	0.8–4.3	900	0.5	18	1.35	100	–30 – +70	19*19*8.6
H6466K	0.95–2	1050	0.7	16	1.4	100	–10 – +60	64*66*26
H1313T	1.71–5.9	800	0.45	18	1.3	100	–30 – +70	12.7*12.7*7.2
H5050A	1.5–3	1500	0.7	17	1.4	100	0 – +60	50.8*49.5*19
H4040A	1.7–3	1200	0.7	16	1.35	200	0 – +60	40*40*20
H1313M	1.71–5.9	800	0.45	18	1.3	100	–30 – +70	12.7*12.7*7.2
H2528C	2.7–6	3500	0.8	16	1.4	200	–30 – +70	25.4*28*14
H3234A	2–4	2000	0.6	16	1.35	100	0 – +60	32*34*21
H1822D	4–5	1000	0.4	18	1.35	60	–30 – +70	18*22*10.4
H2123B	4–8	4000	0.6	18	1.35	60	0 – +60	21*22.5*15
H1220D	5–6.5	800	0.5	18	1.3	60	–30 – +70	12*20*9.5
H1623D	5–6.5	800	0.5	18	1.3	50	–30 – +70	16*23*9.7
H1319C	6–12	4000	0.5	18	1.3	50	0 – +60	13*19*12.7
H0915D	7–18	6000	0.6	17	1.35	30	–30 – +70	8.9*15*7.8

SHINHOM